

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
09 January 2025 (09.01.2025)



(10) International Publication Number
WO 2025/010169 A1

- (51) **International Patent Classification:**
H01L 21/67 (2006.01) *G01L 19/08* (2006.01)
- (21) **International Application Number:**
PCT/US2024/035490
- (22) **International Filing Date:**
26 June 2024 (26.06.2024)
- (25) **Filing Language:** English
- (26) **Publication Language:** English
- (30) **Priority Data:**
63/524,701 03 July 2023 (03.07.2023) US
18/750,894 21 June 2024 (21.06.2024) US
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- (81) **Designated States** (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA,

NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

- (84) **Designated States** (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))

(54) **Title:** MINI ENVIRONMENT INSTRUMENTED WAFER

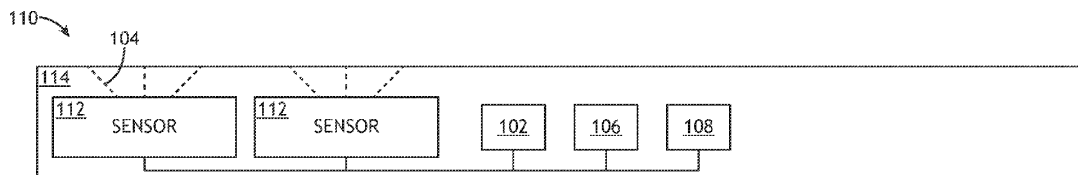


FIG. 1

(57) **Abstract:** A system and method for measuring substrate processing conditions are disclosed. The system may include an instrumented substrate including a substrate body. The instrumented substrate may include one or more sensors configured to measure one or more conditions of the at least one of the substrate body or of an external environment proximate to a surface of the substrate body. The substrate body may include channels within the substrate body connected to the one or more sensors. Each channel may include an open channel configured to allow a flow of gas through the open channel.

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